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**RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 1765**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Diane C. Boyd et al.	Docket:	YOR920030335US1 (16900)
Serial No.:	10/725,848	Examiner:	Patricia Ann George
Filed:	December 2, 2003	Art Unit:	1765
For:	ULTRA-THIN Si MOSFET DEVICE STRUCTURE AND METHOD OF MANUFACTURE	Dated:	May 19, 2006
		Confirmation No:	3237

Mail Stop AF
Commissioner for Patents
United States Patent Office
Alexandria, VA 22313-1450

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*entered per REC
filed 7/21/06
la*


Sir:

In response to the Office Action dated March 22, 2006, applicants submit the following amendments and remarks for entry of record in the above-identified patent application..

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on May 19, 2006.

Dated: May 19, 2006


Leslie S. Szivos, Ph.D.